

**Amendments to the Claims:**

The following listing of claims replaces all other versions of claims previously presented.

**Listing of Claims:**

Claim 1 (cancelled)

Claim 2 (currently amended): A semiconductor device, comprising:  
a semiconductor substrate;  
a first insulating film formed on said semiconductor substrate;  
a polysilicon resistor film formed on said first insulating film;  
a second insulating film formed on said resistor film;  
a high heat conductor film consisting of a highly heat-conducting material formed on  
said second insulating film, said high heat conductor film formed in a predetermined area  
including an area above said resistor film; and  
a pair of terminal wirings formed on said second insulating film and connected to  
said resistor film,

wherein a thickness of said high heat conductor film is thicker than a thickness of  
said resistor film.

Claim 3 (original): The semiconductor device according to claim 2, wherein the  
thickness of said high heat conductor film is twice the thickness of said resistor film or  
thicker.

Claim 4 (original): The semiconductor device according to claim 2, wherein a width  
of said high heat conductor film is wider than a width of said resistor film.

Claim 5 (original): The semiconductor device according to claim 2, wherein said high heat conductor film is united with one of said terminal wirings.

Claim 6 (currently amended): A semiconductor device, comprising:  
a semiconductor substrate;  
a first insulating film formed on said semiconductor substrate;  
a polysilicon resistor film formed on said first insulating film;  
a second insulating film formed on said resistor film;  
a high heat conductor film consisting of a highly heat-conducting material formed on said second insulating film, said high heat conductor film formed in a predetermined area including an area above said resistor film; and  
a pair of terminal wirings formed on said second insulating film and connected to said resistor film,  
wherein a thickness of said second insulating film is thinner than a thickness of said resistor film, and a thickness of said high heat conductor film is thicker than a thickness of said resistor film.

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